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ABSTRACT OF THE DISCLOSURE

FLUID MATERIAL FILLING APPARATUS AND RELATED FILLING METHOD

A vacuum pump depressurizes a scavenging chamber to discharge the air or gas residing in a via hole. Then, a paste chamber provided adjacent to the
5 scavenging chamber moves on the scavenged via hole. A squeezing unit provided in the paste chamber pushes a conductive paste into the via hole. Keeping the inside space of the via hole in a depressurized condition is effective to let the conductive paste enter deeply into the via hole. The inside
10 space of the via hole is entirely filled with the conductive paste.

(Figure 1)



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